

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
19 August 2004 (19.08.2004)

PCT

(10) International Publication Number
WO 2004/070790 A2

(51) International Patent Classification⁷: **H01L**
(21) International Application Number:
PCT/US2004/002985
(22) International Filing Date: 3 February 2004 (03.02.2004)
(25) Filing Language: English
(26) Publication Language: English
(30) Priority Data:
60/444,205 3 February 2003 (03.02.2003) US

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

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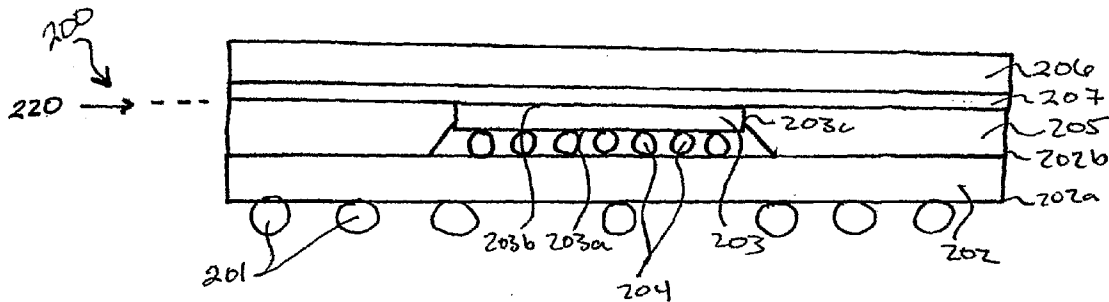
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— without international search report and to be republished upon receipt of that report

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

(54) Title: MOLDED HIGH DENSITY ELECTRONIC PACKAGING STRUCTURE FOR HIGH PERFORMANCE APPLICATIONS



(57) Abstract: A thermally enhanced ball grid array package is disclosed. The package includes a base layer element and a flip chip die mounted on the base layer element. The die has a first surface electrically coupled to the base layer element, a second surface opposite to the first surface, and lateral sides. A molding compound encapsulates the base layer element and the lateral sides of the die. A surface is formed of the second surface of the die and an upper surface of the molding compound. A material is disposed on the surface, and a heat spreader is mounted on the material.

WO 2004/070790 A2